

ASIC COMPANION NETWORK MOLDED MEDIUM BODY SOIC .225" WIDE, WITH .050" LEAD PITCH - 16 PIN

- Used in conjunction with Mosys MD9000 series MDRAMs and Tseng Labs ET6000 Graphics Chip Sets
- Compliant leads for thermal expansion
- Miniaturized circuitry and packaging for space reduction

Model 4816P-003-221/221

B® Resistor Network SOIC

Electrical Characteristics

Resistance

| | |
|---------------------------------|-----------------|
| R1 | .220 ohms |
| R2 | .220 ohms |
| Absolute Tolerance | ±2% |
| Temperature Coefficient | ±100ppm/°C |
| TCR Tracking | ±150ppm/°C |
| Temperature Range | -55°C to +125°C |
| Maximum Operating Voltage | 50VDC/or √ PR |
| Insulation Resistance..... | 10,000 MΩ |

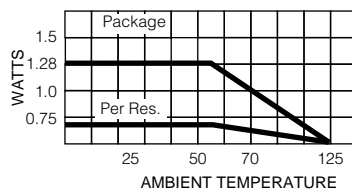
Product Reliability

| | |
|-----------------------------------|---------|
| | ΔR MAX. |
| Thermal Shock..... | ±0.25% |
| Power Condition | ±0.50% |
| Vibration..... | ±0.25% |
| Low Temperature Storage | ±0.25% |
| High Temperature Exposure | ±0.50% |
| Low Temperature Operation | ±0.25% |
| Load Life | ±1.0% |
| Moisture Resistance | ±0.5% |
| Resistance to Soldering Heat | ±0.25% |
| Short Time Overload..... | ±0.25% |

Physical Characteristics

| | |
|----------------------|-----------------------|
| Lead Material | Copper, solder coated |
| Body Material | Molded epoxy |
| Std. Packaging | Tape & reel |

PACKAGE POWER TEMPERATURE DERATING CURVE



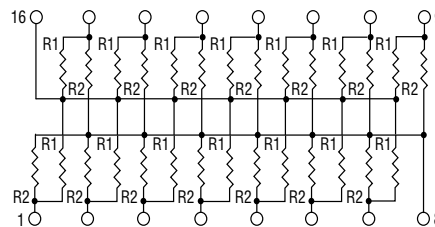
Package Power Ratings at 70°C

16 Pin 1.28 watts Max.

Power Per Resistor at 70°C

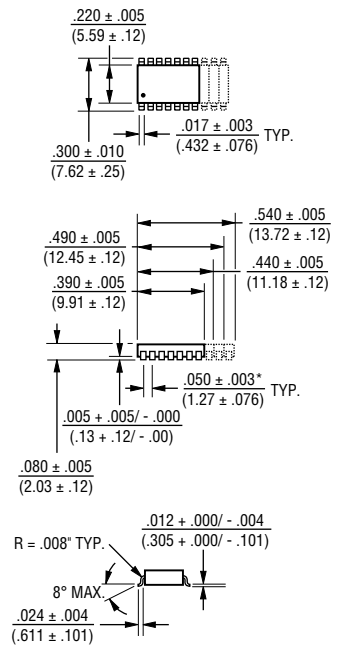
..... .080 watts Max.

SCHEMATIC



DIMENSIONS

4800P



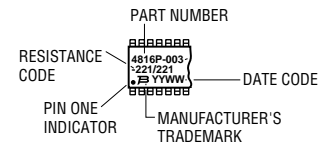
Lead coplanarity .004 inch max. at mounting surface.

Governing dimensions are in inches. Dimensions in parentheses are metric (mm) and are approximate.

*Terminal centerline to centerline measurements made at point of emergence of the lead from the body.

TYPICAL PART MARKING

Represents total content. Layout may vary.



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